

SMT inductors

SIMID series, SIMID 1210-01

Series/Type: B82412A

Date: March 2008

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B82412A

SIMID 1210-01

<u>SMD</u>

Size 1210 (EIA) or 3225 (IEC) Rated inductance 0.010 μ H to 10 μ H Rated current 90 mA to 700 mA

Construction

- Ceramic or ferrite core
- Single-layer winding fixed by glue
- Ultrasonic-welded winding

Features

- Low height
- High Q factor
- High resonance frequency
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- RoHS-compatible

Applications

- Filtering of supply voltages, coupling, decoupling
- Antenna systems
- Infotainment
- Telecommunications
- Industrial electronics

Terminals

- Base material CuSn6
- Layer composition Cu, Ag (lead-free)
- Electro-plated

Marking

- No marking on component
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing units

- \blacksquare 8-mm blister tape, wound on 180-mm or 330-mm \varnothing reel
- Packing units:
 - 180-mm reel: 2500 pcs./reel 330-mm reel: 10000 pcs./reel

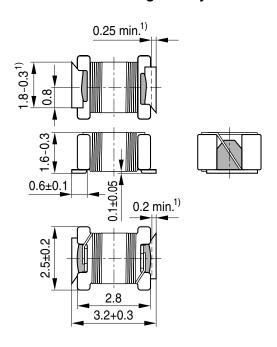


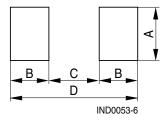
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Dimensional drawing and layout recommendation





A	В	С	D
2.7	1.15	2.1	4.4

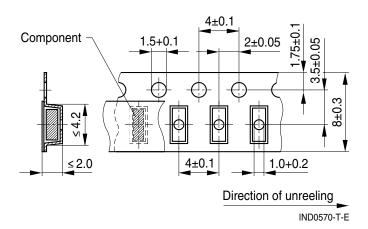
1) Soldering area

IND0052-V-E

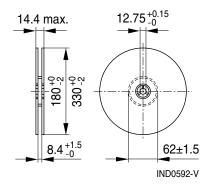
Dimensions in mm

Taping and packing

Blister tape



Reel



Dimensions in mm



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Technical data and measuring conditions

Rated inductance L _R	Measured with impedance analyzer Agilent 4294A at frequency f_L , 0.1 V, 20 $^{\circ}$ C
Q factor Q _{min}	Measured with impedance analyzer Agilent 4294A at frequency $f_{\rm Q}$, 20 °C
Rated temperature T _R	85 °C
Rated current I _R	Maximum permissible DC with inductance decrease $\Delta L/L_0 \le 10\%$ and temperature increase of ≤ 20 K at rated temperature
Self-resonance frequency f _{res,min}	Measured with network analyzer Agilent 8753D, 20 °C
DC resistance R _{max}	Measured at 20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: (245 \pm 5) °C, (5 \pm 0.3) s Wetting of soldering area \geq 95% (based on IEC 60068-2-58)
Resistance to soldering heat	260 °C, 40 s (as referenced in JEDEC J-STD 020C)
Climatic category	55/125/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C +125 °C Packaged: -25 °C +40 °C, ≤ 75% RH
Weight	Approx. 40 mg



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Characteristics and ordering codes

L _R	Tolerance	f_{L}	Q _{min}	f _Q	I _R	R _{max}	f _{res,min}	Ordering code ¹⁾
μΗ		MHz		MHz	mA	Ω	MHz	(Ø 180-mm reel)
Core ma	Core material: ceramic							
0.010	±20% ≙ M	10	25	100	700	0.10	4000	B82412A3100M000
0.012		10	25	100	700	0.10	3500	B82412A3120M000
0.015		10	25	100	640	0.12	3000	B82412A3150M000
0.018		10	30	100	640	0.12	2700	B82412A3180M000
0.022	±5% ≙ J	10	30	100	600	0.12	2400	B82412A3220+000
0.027	±10% ≙ K	10	20	50	600	0.15	2200	B82412A3270+000
0.033		10	25	50	540	0.17	2000	B82412A3330+000
0.039		10	25	50	500	0.18	1700	B82412A3390+000
0.047		10	25	50	470	0.22	1600	B82412A3470+000
0.056		10	30	50	460	0.23	1400	B82412A3560+000
0.068		10	30	50	440	0.25	1350	B82412A3680+000
0.082		10	30	50	430	0.27	1100	B82412A3820+000
0.10		10	30	50	400	0.30	1000	B82412A3101+000
0.12		1	25	30	380	0.35	900	B82412A3121+000
0.15		1	25	30	370	0.36	820	B82412A3151+000
0.18		1	25	30	340	0.42	700	B82412A3181+000
0.22		1	25	30	320	0.48	630	B82412A3221+000
0.27		1	30	30	300	0.55	570	B82412A3271+000
0.33		1	30	30	280	0.65	550	B82412A3331+000
0.39		1	30	30	260	0.75	500	B82412A3391+000
0.47		1	30	30	225	1.00	450	B82412A3471+000
0.56		1	30	30	200	1.20	430	B82412A3561+000
0.68		1	30	30	180	1.40	400	B82412A3681+000
0.82		1	30	30	150	2.00	380	B82412A3821+000

Closer tolerances and special versions on request.

Replace the + by the code letter for the required inductance tolerance.
For reel size Ø 330 mm the last digit has to be an »8«. Example: B82412A3100M008



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Characteristics and ordering codes

L _R	Tolerance	f _L	Q _{min}	f _Q	I _R	R _{max}	f _{res,min}	Ordering code ¹⁾
μΗ		MHz		MHz	mA	Ω	MHz	(Ø 180-mm reel)
Core ma	Core material: ferrite							
1.0	±5% ≙ J	1	30	7.96	330	0.45	300	B82412A1102+000
1.2	±10% ≙ K	1	30	7.96	310	0.50	260	B82412A1122+000
1.5		1	30	7.96	300	0.55	240	B82412A1152+000
1.8		1	30	7.96	290	0.60	220	B82412A1182+000
2.2		1	30	7.96	270	0.65	200	B82412A1222+000
2.7		1	30	7.96	220	1.05	180	B82412A1272+000
3.3		1	30	7.96	200	1.10	160	B82412A1332+000
3.9		1	30	7.96	190	1.35	150	B82412A1392+000
4.7		1	35	7.96	160	1.80	140	B82412A1472+000
5.6		1	35	7.96	140	2.70	125	B82412A1562+000
6.8		1	35	7.96	120	3.50	115	B82412A1682+000
8.2		1	35	7.96	110	3.80	100	B82412A1822+000
10		1	35	7.96	90	5.50	95	B82412A1103+000

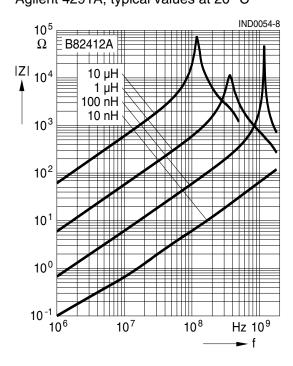
Closer tolerances and special versions on request.

Replace the + by the code letter for the required inductance tolerance.
For reel size Ø 330 mm the last digit has to be an »8«. Example: B82412A1102M008

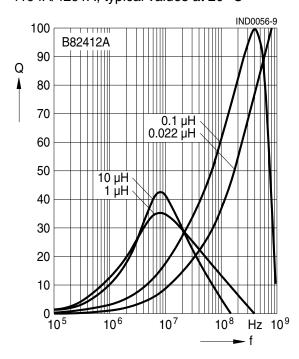


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Impedance IZI versus frequency f measured with impedance analyzer Agilent 4291A, typical values at 20 °C

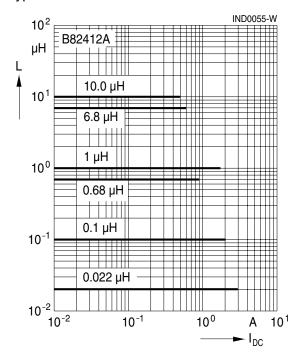


Q factor versus frequency f measured with impedance analyzer Agilent 4194A/4291A, typical values at 20 °C

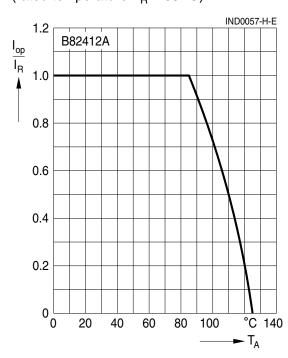


<u>SMD</u>

Inductance L versus DC load current I_{DC} measured with LCR meter Agilent 4275A, typical values at 20 °C



Current derating I_{op}/I_R versus ambient temperature T_A (rated temperature $T_B = 85$ °C)





Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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